Title (en)

USE OF A THERMALLY CURABLE AQUEOUS COMPOSITION AS A BINDER FOR SUBSTRATES

Title (de)

VERWENDUNG EINER THERMISCH HÄRTBAREN WÄSSRIGEN ZUSAMMENSETZUNG ALS BINDEMITTEL FÜR SUBSTRATE

Title (fr)

UTILISATION D'UNE COMPOSITION THERMODURCISSABLE EN TANT QUE LIANT POUR DES SUBSTRATS

Publication

EP 1913083 A1 20080423 (DE)

Application

EP 06792595 A 20060728

Priority

- EP 2006064766 W 20060728
- DE 102005037113 A 20050803

Abstract (en)

[origin: WO2007014906A1] The present invention relates to the use of a thermally curable aqueous composition comprising dispersed polymer particles of at least a) one polymer A1 containing 98-100% by weight of ethylenically unsaturated monomers A, where up to 20% by weight of the monomers A may contain glycidyl and/or hydroxyl groups and/or amine/amide groups and the polymer contains = 5% by weight of an a,ß-ethylenically unsaturated mono- or dicarboxylic acid and at least 1% by weight of acrylonitrile in copolymerized form, and 0-5% by weight of a bi- or multifunctional monomer, and b) one polymer A2 which is soluble in serum and contains, in copolymerized form, 60-100% by weight of at least one a,ß-ethylenically unsaturated mono- or dicarboxylic acid whose carboxylic acid groups may form an anhydride group, salts or mixtures thereof, c) and a polyfunctional crosslinker or mixtures thereof, d) and optionally di- or trivalent metal ions which are added in the form of hydroxides, oxides, carbonates or hydrogencarbonates, as binders for substrates.

IPC 8 full level

C08L 33/00 (2006.01); **D04H 1/587** (2012.01)

CPC (source: EP US)

C09J 133/14 (2013.01 - EP US); **D04H 1/64** (2013.01 - EP US); C08L 2666/04 (2013.01 - EP US)

Citation (search report)

See references of WO 2007014906A1

Cited by

WO2011131279A1

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU LV MC NL PL PT RO SE SI SK TR

DOCDB simple family (publication)

DE 102005037113 A1 20070208; CN 101278005 A 20081001; EP 1913083 A1 20080423; JP 2009503215 A 20090129; US 2008214716 A1 20080904; WO 2007014906 A1 20070208

DOCDB simple family (application)

DE 102005037113 A 20050803; CN 200680036675 A 20060728; EP 06792595 A 20060728; EP 2006064766 W 20060728; JP 2008524495 A 20060728; US 99761806 A 20060728